

Trouble Shooting Guide For Encapsulation/Transfer or Compression Molding

Defect: Blistering, heavy section

- 1.) Increase cure.
- 2.) Close mold slowly on low pressure, then apply high pressure to purge gas.
- 3.) Vent mold.
- 4.) Preheat to eliminate moisture. Increase preform temperature.
- 5.) Breathe mold as soon as possible.
- 6.) Increase pressure.
- 7.) Use stiffer material.
- 8.) Lower mold temperature.
- 9.) Check mold temperature for uniformity.
- 10.) Vent mold at dead ends with vent pins.

Defect: Porosity (not filled out in every section)

- 1.) Try a range of plasticities for best grade.
- 2.) Increase pressure.
- 3.) Lower temperature.
- 4.) Close mold faster if external porosity, apply high pressure sooner; close mold slower if internal porosity, apply low pressure longer.
- 5.) Preheat material.
- 6.) Adjust charge weight.
- 7.) Try a higher density material to obtain greater "ac pressure" in the mold.
- 8.) Breathe mold earlier.
- 9.) Use semi-positive molds to minimize porosity.

Defect: Mold sticking

- 1.) Raise mold temperature.
- 2.) Preheat to eliminate moisture.
- 3.) Clean mold.
- 4.) Use stiffer material.
- 5.) Remove dents and undercuts in mold cavity and force.
- 6.) Polish mold.
- 7.) Increase cure.
- 8.) Lower pressure, softer material if plunger molding.
- 9.) Check knockout pin adjustment.
- 10.) Be sure cavities have sufficient draft.

Defect: Dull surface

- 1.) Adjust mold temperature- usually reduce temperature for better appearance.
- 2.) Polish mold.
- 3.) Chrome plate.
- 4.) Close mold more slowly

Defect: Orange peel (rough, pimply surface)

- 1.) Close slowly on low pressure. Delay 2 sec. before applying high pressure.
- 2.) Preheat (radio frequency).
- 3.) Use stiffer material.
- 4.) Use finer ground material.
- 5.) Use large preforms and as few as possible.
- 6.) Use lower mold temperature.

Defect: Pitted surface

- 1.) Use stiffer material.
- 2.) Preheat.

Defect: Clouded or segregated surface

- 1.) Reduce molding temperature (for colors, 300 to 310° F.).
- 2.) Preheat preforms.
- 3.) Adjust plasticity.
- 4.) Adjust pressure and closing speed.

Defect: "L" marks

- 1.) Close slowly, longer on low pressure, no breathe, then high pressure.
- 2.) Use stiffer material.
- 3.) Lower mold temperature.
- 4.) Increase charge weight
- 5.) Shape preforms more closely to piece.
- 6.) Increase pressure.

Defect: Warped piece

- 1.) Heat mold more uniformly.
- 2.) Use stiffer material.
- 3.) Preheat if soft plasticity.
- 4.) Increase cure.
- 5.) Use lower shrinkage material and/or material more rigid at discharge.
- 6.) Redesign mold; use wider knockout pins.
- 7.) Adjust temperature of force and cavity - lower temperature may reduce warpage.
- 8.) Preheat for irregular shaped pieces.
- 9.) Cool uniformly use shrink fixtures.

Defect: Cracking after molding

- 1.) Increase wall thickness around inserts.
- 2.) Check knockout pins.
- 3.) Correct size of shrink fixture.
- 4.) Use more flexible material.
- 5.) Increase radii and ribs.
- 6.) Oven anneal 2 hr. at 200° F

Defect: Poor electrical properties

- 1.) Close slowly
- 2.) Preheat 1/2 hr. at 185° F.
- 3.) Increase cure.
- 4.) Reduce temperature.
- 5.) Use stiffer grade.

Defect: Weak mechanically

- 1.) Increase temperature.
- 2.) Increase cure.
- 3.) Increase pressure.
- 4.) High frequency preheat.
- 5.) Increase charge.
- 6.) Afterbake to increase strength, if economical. Try 2 hr. at 250° F.

Defect Pimpling

- 1.) Breathe mold.
- 2.) Use higher fines material.
- 3.) Use softer material.
- 4.) R. F. preheat.
- 5.) Lower mold temperature.

Defect: Burned marks

- 1.) Reduce preheat temperature.
- 2.) Reduce mold temperature.
- 3.) Open gates; be sure vents are clear; check plunger travel time to see if it is between 5 and 12 sec. (faster close will entrap gas; slower close causes burn marks).
- 4.) Avoid or minimize breathing.

Defect: Thick flash

- 1.) Reduce mold charge.
- 2.) Reduce mold temperature.
- 3.) Increase high pressure.
- 4.) Close on low, apply high pressure sooner.
- 5.) Eliminate breathing, follow (4.).
- 6.) Use softer grade material for more pressure.
- 7.) Be sure of 0.002-in. between force and cavity.
- 8.) Be sure overflow grooves are clean.
- 9.) Reduce transfer pressure and/or increase clamping pressure.

Reference: Modern Plastics Encyclopedia
McGraw Hill Inc.

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